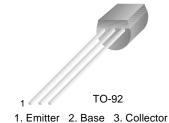


## 2N5401

## **Amplifier Transistor**

- Collector-Emitter Voltage: V<sub>CEO</sub>= 150V
  Collector Dissipation: P<sub>C</sub> (max)=625mW
- Suffix "-C" means Conter Collector (1. Emitter 2. Collector 3. Base)



# **PNP Epitaxial Silicon Transistor**

# **Absolute Maximum Ratings** T<sub>a</sub>=25°C unless otherwise noted

Symbol	Parameter	Value	Units	
$V_{CBO}$	Collector-Base Voltage	-160	V	
V <sub>CEO</sub>	Collector-Emitter Voltage	-150	V	
V <sub>EBO</sub>	Emitter-Base Voltage	-5	V	
I <sub>C</sub>	Collector Current	-600	mA	
P <sub>C</sub>	Collector Dissipation	625	mW	
TJ	Junction Temperature	150	°C	
T <sub>STG</sub>	Storage Temperature	-55 ~ 150	°C	

## **Electrical Characteristics** T<sub>a</sub>=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
BV <sub>CBO</sub>	Collector-Base Breakdown Voltage	$I_C = -100 \mu A, I_E = 0$	-160			V
BV <sub>CEO</sub>	* Collector-Emitter Breakdown Voltage	$I_C = -1 \text{mA}, I_B = 0$	-150			V
BV <sub>EBO</sub>	Emitter-Base Breakdown Voltage	$I_E = -10\mu A, I_C = 0$	-5			V
I <sub>CBO</sub>	Collector Cut-off Current	V <sub>CB</sub> = -120V, I <sub>E</sub> =0			-50	nA
I <sub>EBO</sub>	Emitter Cut-off Current	$V_{EB}$ = -3V, $I_{C}$ =0				nA
h <sub>FE</sub>	* DC Current Gain	I <sub>C</sub> = -1mA, V <sub>CE</sub> = -5V I <sub>C</sub> = -10mA, V <sub>CE</sub> = -5V I <sub>C</sub> = -50mA, V <sub>CE</sub> = -5V	30 60 50		240	
V <sub>CE</sub> (sat)	* Collector-Emitter Saturation Voltage	$I_C$ = -10mA, $I_B$ = -1mA $I_C$ = -50mA, $I_B$ = -5mA			-0.2 -0.5	V V
V <sub>BE</sub> (sat)	* Base-Emitter Saturation Voltage	I <sub>C</sub> = -10mA, I <sub>B</sub> = -1mA I <sub>C</sub> = -50mA, I <sub>B</sub> = -5mA			-1 -1	V V
f <sub>T</sub>	Current Gain Bandwidth Product	I <sub>C</sub> = -10mA, V <sub>CE</sub> = -10V, f=100MHz	100		400	MHz
C <sub>ob</sub>	Output Capacitance	V <sub>CB</sub> = -10V, I <sub>E</sub> =0, f=1MHz			6	pF
N <sub>F</sub>	Noise Figure	$I_C$ = -250μA, $V_{CE}$ = -5V $R_S$ =1K $\Omega$ f=10Hz to 15.7KHz			8	dB

\* Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%

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# **Typical Characteristics**

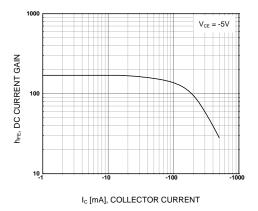


Figure 1. DC current Gain

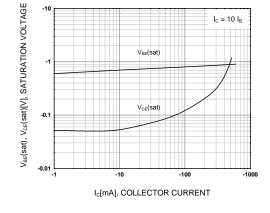


Figure 2. Base-Emitter Saturation Voltage Collector-Emitter Saturation Voltage

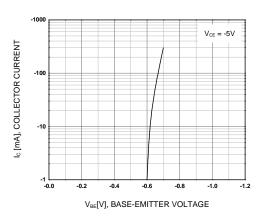


Figure 3. Base-Emitter On Voltage

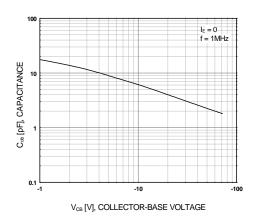


Figure 4. Output Capacitance

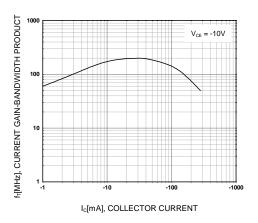
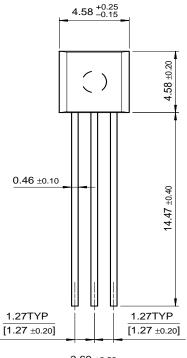


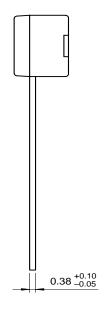
Figure 5. Current Gain Bandwidth Product

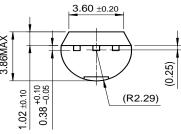
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# **Package Dimensions**

TO-92







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